

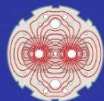


# The Endcap Timing Layer detector for the CMS Phase-2 upgrade

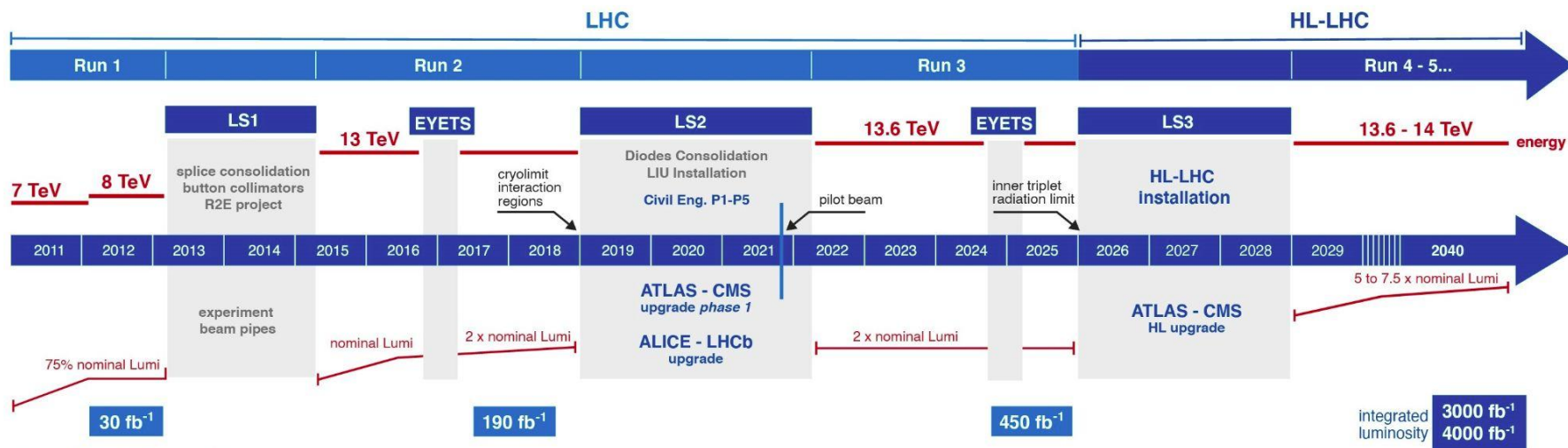
Lazar Markovic on behalf of the CMS collaboration

Elba Island, 31/05/2023, FAST 2023 workshop

# High Luminosity LHC (HL-LHC)

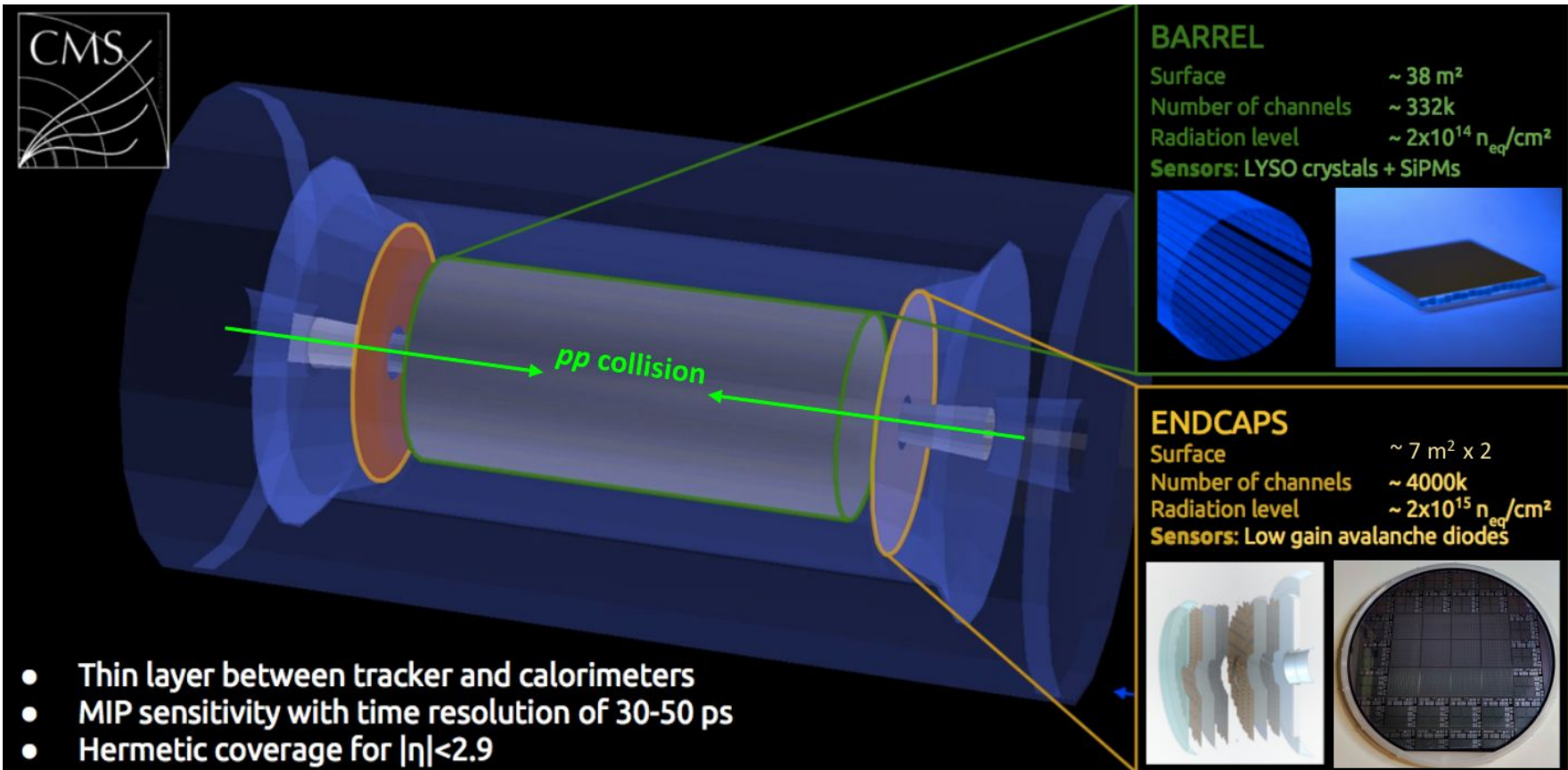


## LHC / HL-LHC Plan



- ❖ Planned phase 2 upgrade will be done between 2026-28
- ❖ This talk is centered around ETL of the CMS
- ❖ For why we need it, check out **Federico's** talk

# MTD design



**CMS**

**BARREL**

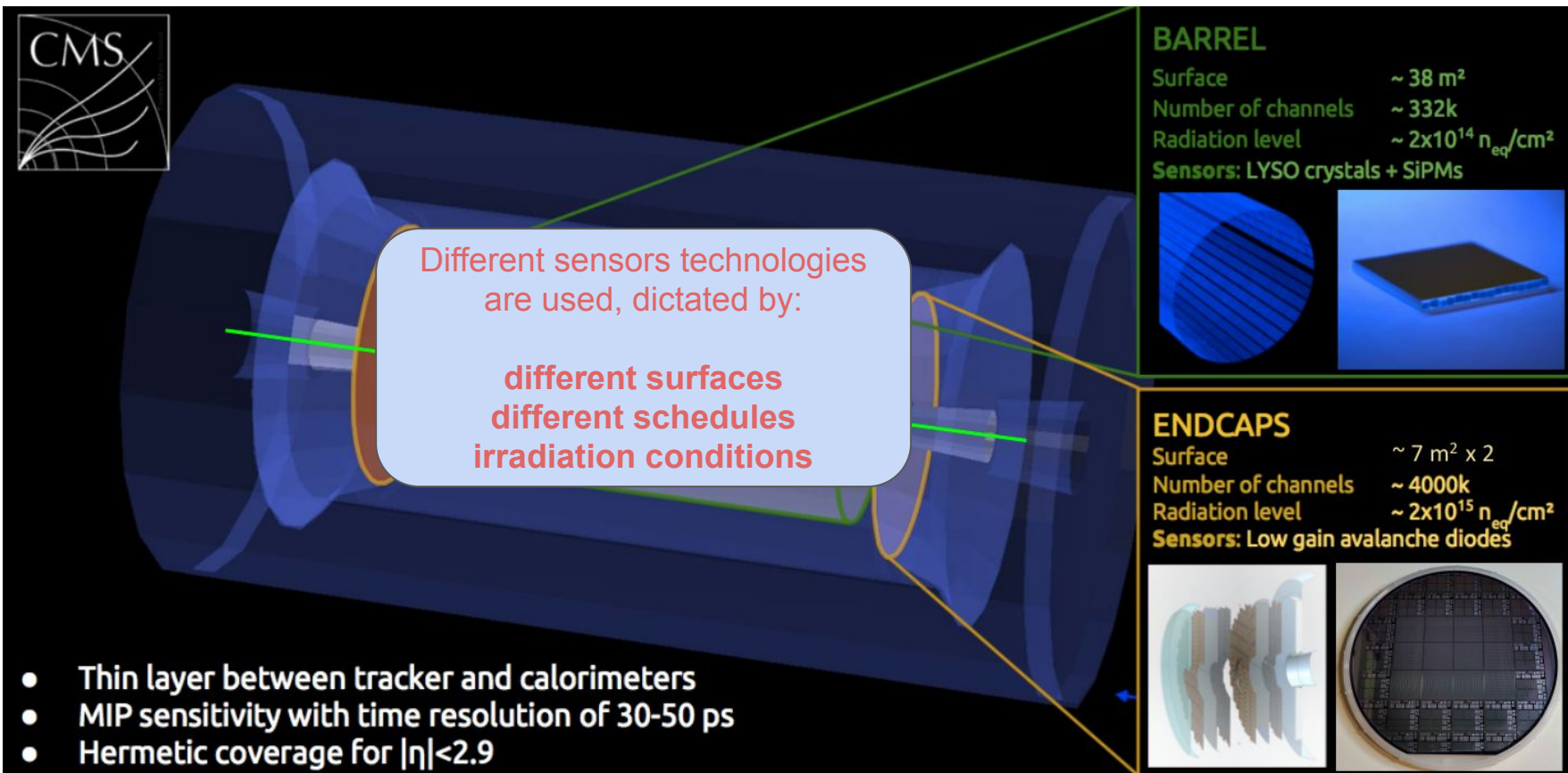
Surface	$\sim 38 \text{ m}^2$
Number of channels	$\sim 332\text{k}$
Radiation level	$\sim 2 \times 10^{14} \text{ n}_{\text{eq}}/\text{cm}^2$
<b>Sensors:</b>	<b>LYSO crystals + SiPMs</b>

**ENDCAPS**

Surface	$\sim 7 \text{ m}^2 \times 2$
Number of channels	$\sim 400\text{k}$
Radiation level	$\sim 2 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$
<b>Sensors:</b>	<b>Low gain avalanche diodes</b>

- Thin layer between tracker and calorimeters
- MIP sensitivity with time resolution of 30-50 ps
- Hermetic coverage for  $|\eta| < 2.9$

# MTD design



**CMS**

Different sensors technologies are used, dictated by:

- different surfaces
- different schedules
- irradiation conditions

**BARREL**

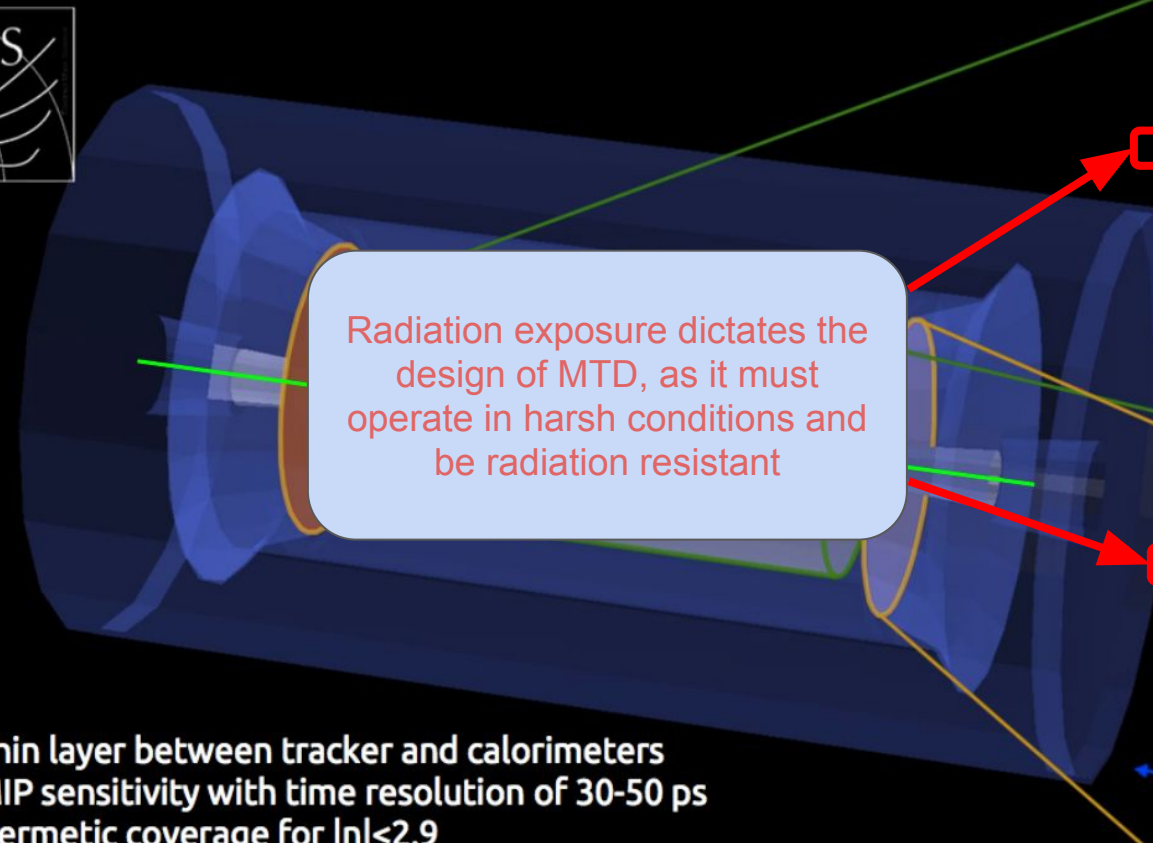
Surface	~ 38 m <sup>2</sup>
Number of channels	~ 332k
Radiation level	~ 2x10 <sup>14</sup> n <sub>eq</sub> /cm <sup>2</sup>
<b>Sensors: LYSO crystals + SiPMs</b>	

**ENDCAPS**

Surface	~ 7 m <sup>2</sup> x 2
Number of channels	~ 4000k
Radiation level	~ 2x10 <sup>15</sup> n <sub>eq</sub> /cm <sup>2</sup>
<b>Sensors: Low gain avalanche diodes</b>	

- Thin layer between tracker and calorimeters
- MIP sensitivity with time resolution of 30-50 ps
- Hermetic coverage for  $|\eta| < 2.9$

# MTD design

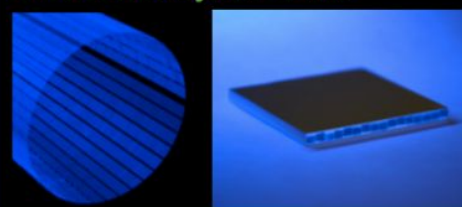


**CMS**

Radiation exposure dictates the design of MTD, as it must operate in harsh conditions and be radiation resistant

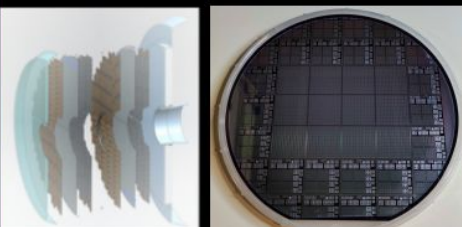
**BARREL**

Surface	~ 38 m <sup>2</sup>
Number of channels	~ 332k
Radiation level	~ 2x10 <sup>14</sup> n <sub>eq</sub> /cm <sup>2</sup>
Sensors: LYSO crystals + SiPMs	



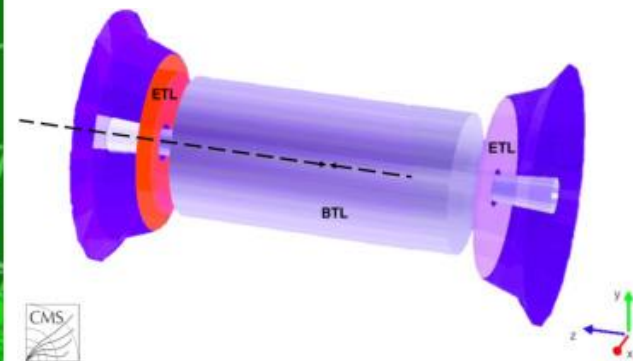
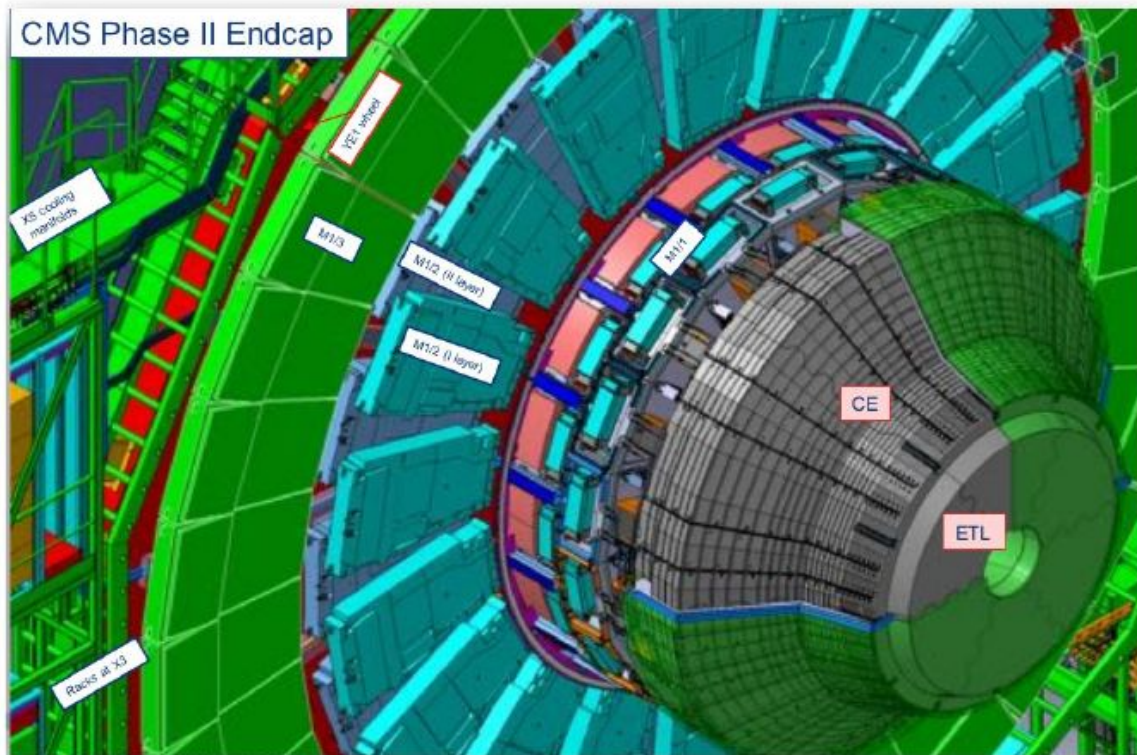
**ENDCAPS**

Surface	~ 7 m <sup>2</sup> x 2
Number of channels	~ 4000k
Radiation level	~ 2x10 <sup>15</sup> n <sub>eq</sub> /cm <sup>2</sup>
Sensors: Low gain avalanche diodes	



- Thin layer between tracker and calorimeters
- MIP sensitivity with time resolution of 30-50 ps
- Hermetic coverage for  $|\eta| < 2.9$

# MTD ETL Design



*MTD design scetch*

*Endcap region of the CMS detector: ETL will be mounted on the CE nose*

# MTD ETL Design

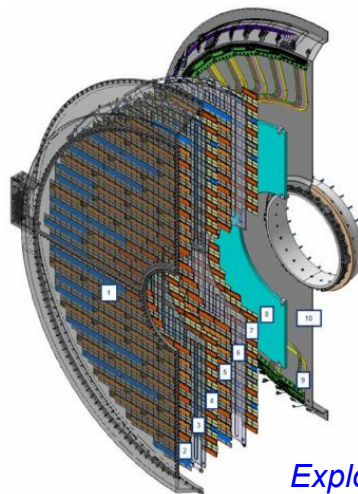
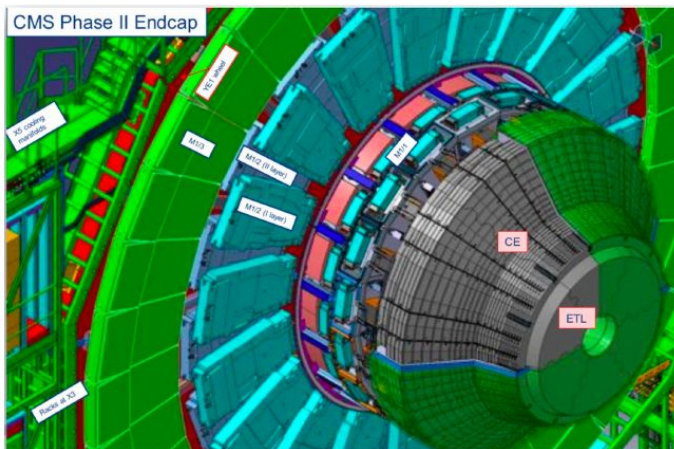
❖ ETL will be mounted on the nose HGCal

❖ Coverage:

- $z = 3$  m from pp interaction
- $0.315 \text{ m} < R < 1.2 \text{ m}$
- Surface  $\sim 14 \text{ m}^2$

❖ 2 double-sided disks for each side

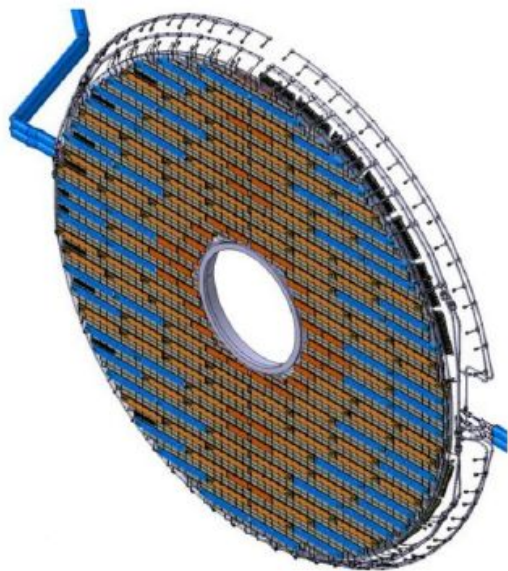
- double-sided disk  $\rightarrow$  large geometrical acceptance
- 2 disks to achieve target time resolution:
  - Single hit resolution  $< 50 \text{ ps}$
  - track resolution  $< 35 \text{ ps}$



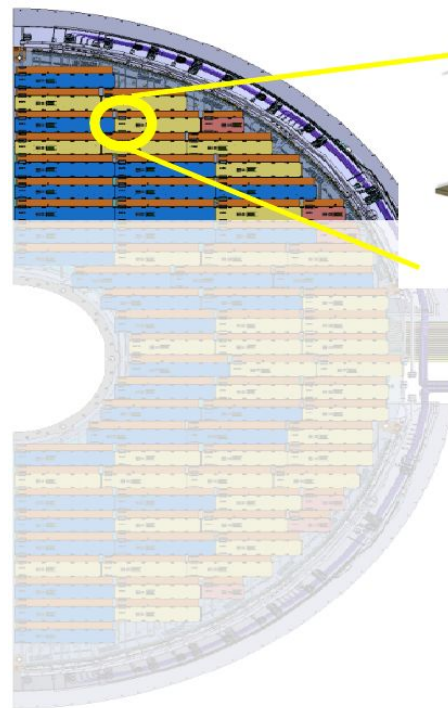
Element	
1	Thermal screen
	Gap between thermal screen and Face 1
2	Face 1 - active layer
3	Front disc
4	Face 2 - active layer
	Gap between Face 2 and Face 3
5	Face 3 - active layer
6	Back disc
7	Face 4 - active layer
	Gap between Face 4 and ETL front moderator
8+9	Patch panels 0 + cables [9] + ETL front moderator
10	ETL back support plate
	Gap between ETL back support plate and CE thermal screen

*Exploded view of one of the ETL disks*

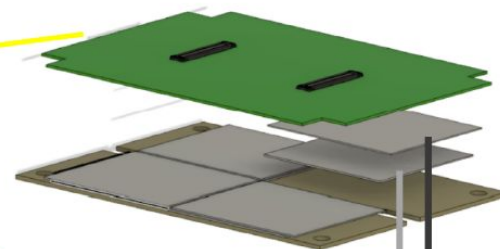
# MTD ETL Design



*ETL disk*

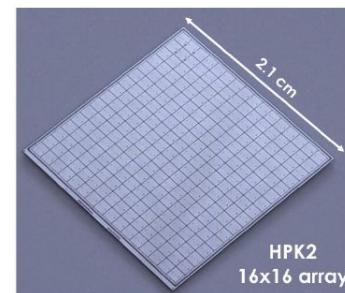


*Zoomed in view of the ETL disk*



LGAD sensors

ETROC



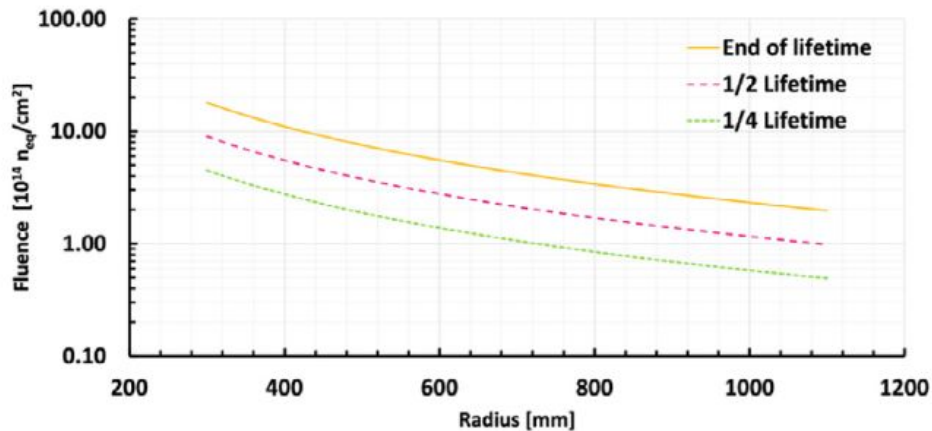
*LGAD sensor matrix*



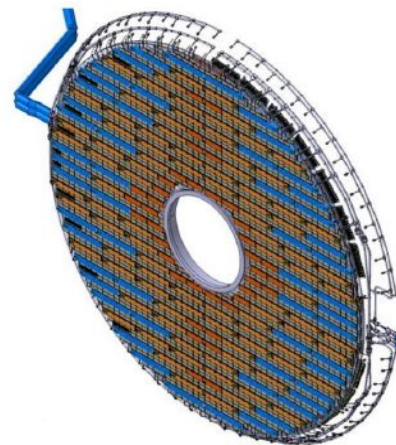
# MTD ETL Design

- ❖  $0.31 \text{ m} < R < 1.2 \text{ m}$
- ❖ Fill-factor  $> 95 \%$  (ratio of active and total detector surface)

Fluence vs radius



Fluence vs radius of the ETL disk

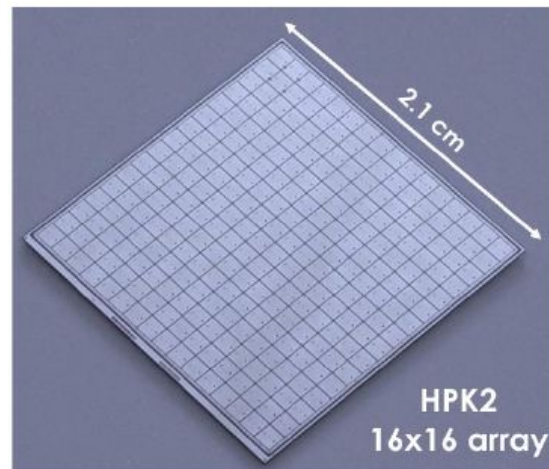
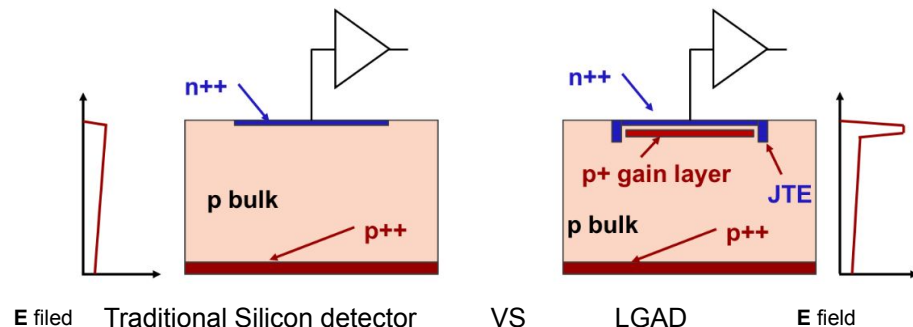


ETL disk

- ❖ Degradation of performances begins at  $\sim 1 \times 10^{15} n_{eq}/cm^2$
- ❖  $\sim 88\%$  ETL will be exposed to  $< 1 \times 10^{15} n_{eq}/cm^2$
- ❖ About  $\sim 12\%$  of ETL will be exposed to  $> 1 \times 10^{15} n_{eq}/cm^2$
- ❖ Tolerable is  $\sim 1.7 \times 10^{15} n_{eq}/cm^2$

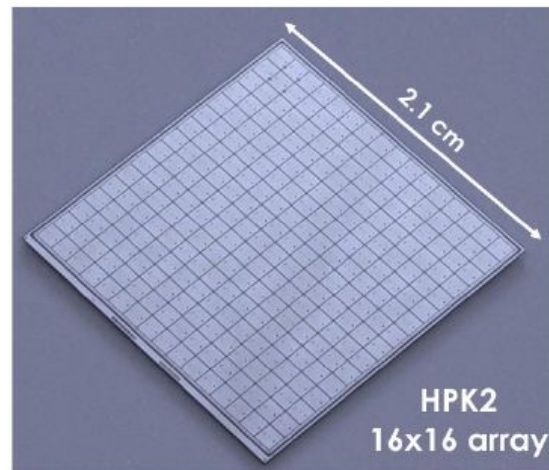
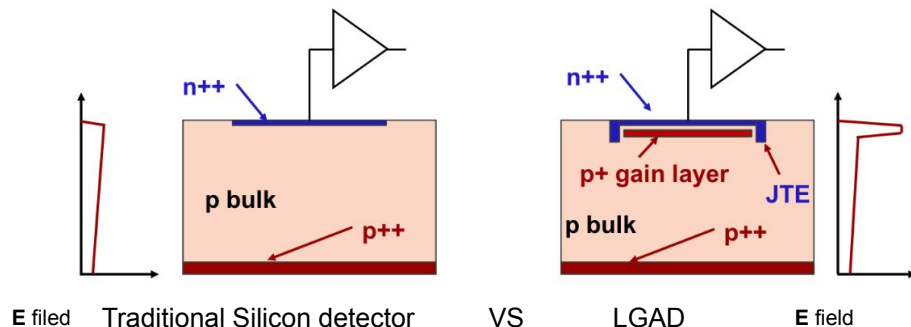
# LGADs: Sensors for ETL

- The ETL sensor will be a 16x16 pad matrix of LGAD sensors
- 1.3 x 1.3 mm<sup>2</sup> pad size
- From the beginning to the end of HL-LHC lifetime, sensors expected to:
  - Achieve single hit time resolution < 50 ps when coupled to the ASIC (30-40 ps for the bare sensor)
  - Deliver > 8 fC of charge
- LGADs suited for radiator: unchanged performance up to  $1.5E15 n_{eq}/cm^2$ , and then slight slow degradation



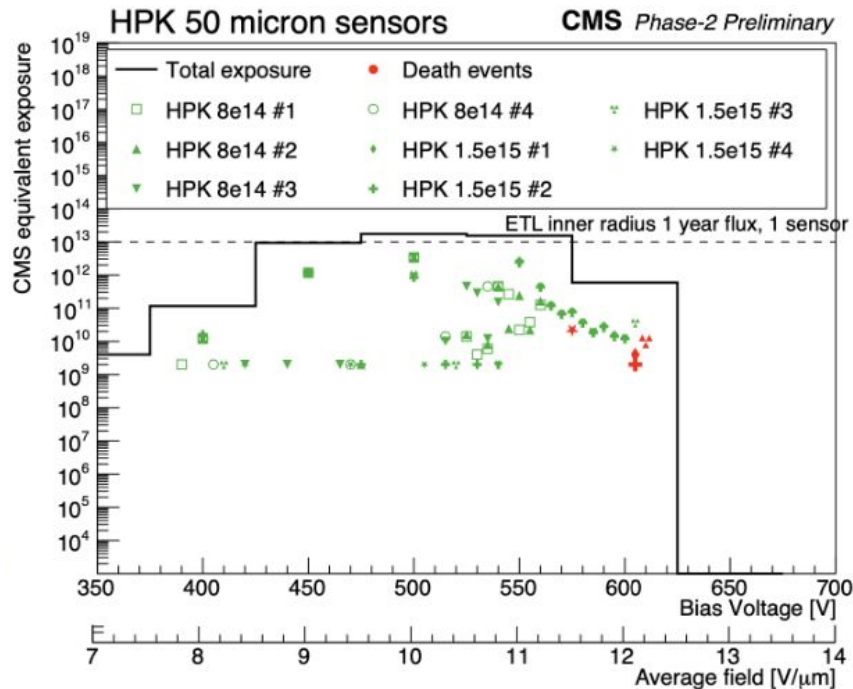
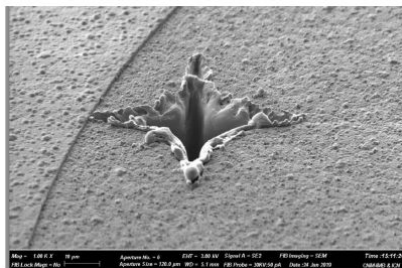
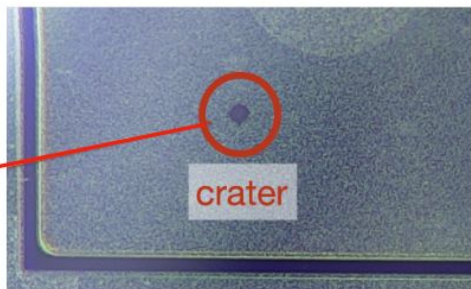
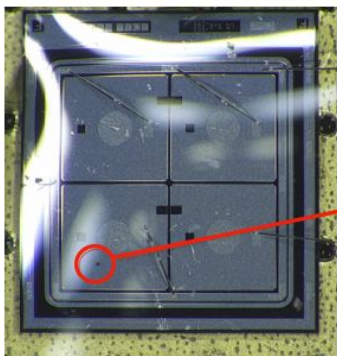
# LGADs: Radiation affected performance

- ❖ There are two major effects that affect the performance:
  - **Gain layer depletion**
  - **Single Event Burnout (SEB)**
- ❖ **Gain layer** can be “recovered” by increasing the bias  $V_{bias}$  (see following slides) and using carbon to harden it
- ❖ **SEB** can be avoided by carefully choosing  $V_{bias}$  range (see following slides)



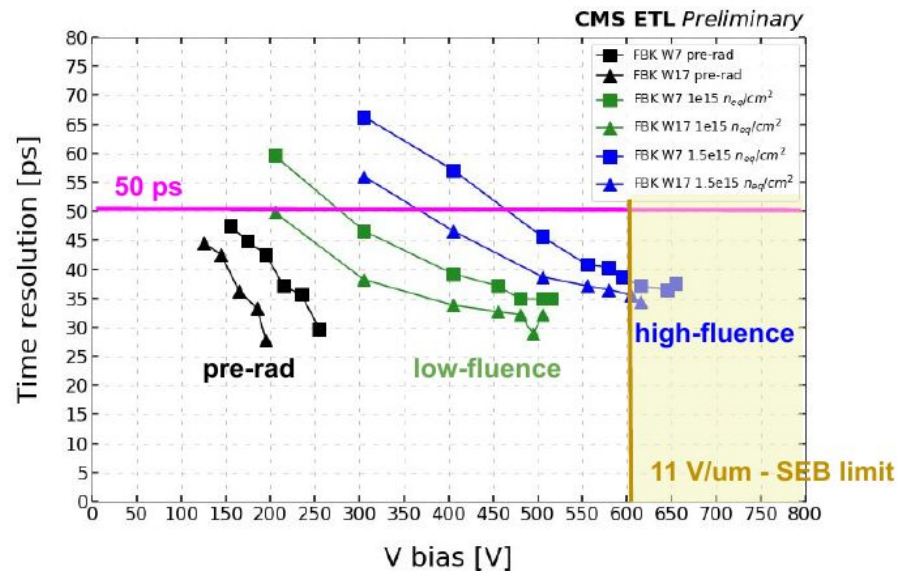
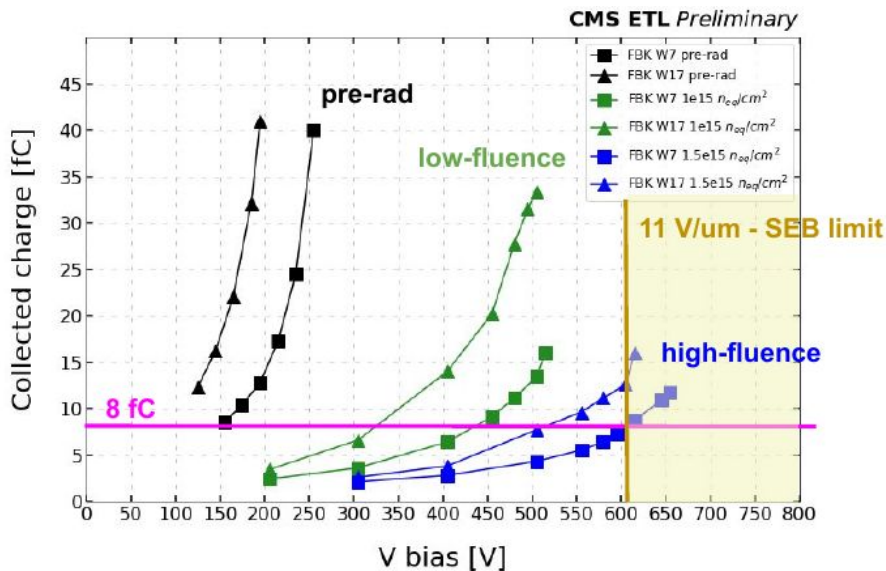
# SEB

- ❖ High-rate test beam at FNAL demonstrate survival of irradiated LGADs at  $> 11 \text{ V}/\mu\text{m}$  under a flux corresponding to  $\sim 1$  year running for the sensors in ETL inner region



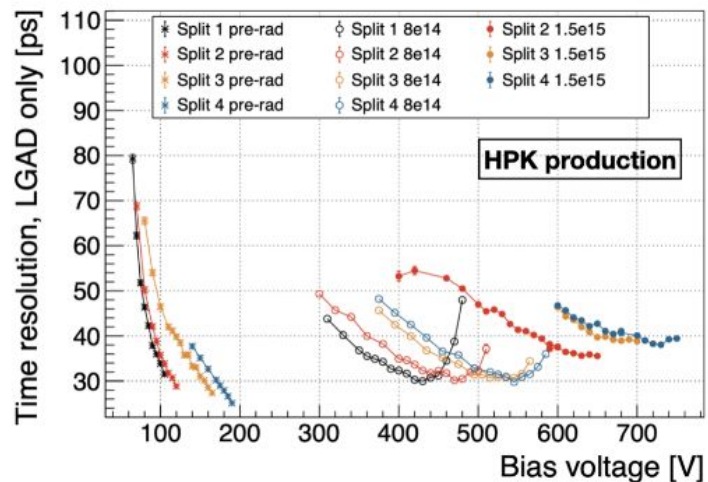
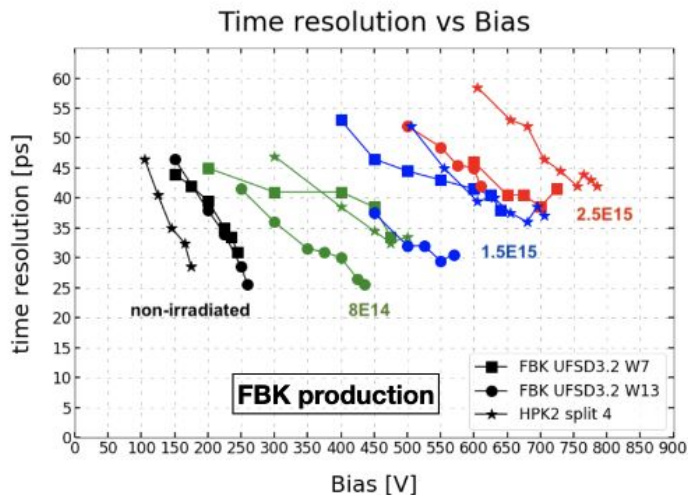
# Performance of LGADs

- ❖ Not safe regime due to Single Event Burn-out process affecting LGADs
  - $E_{\text{bulk}} < 11 \text{ V}/\mu\text{m}$
  - An incoming particle releases a lot of energy over a small volume, 5-10  $\mu\text{m}$
  - The local electric field is high enough to create a conductive channel
  - The energy stored in the sensor capacitance discharges burning the sensor



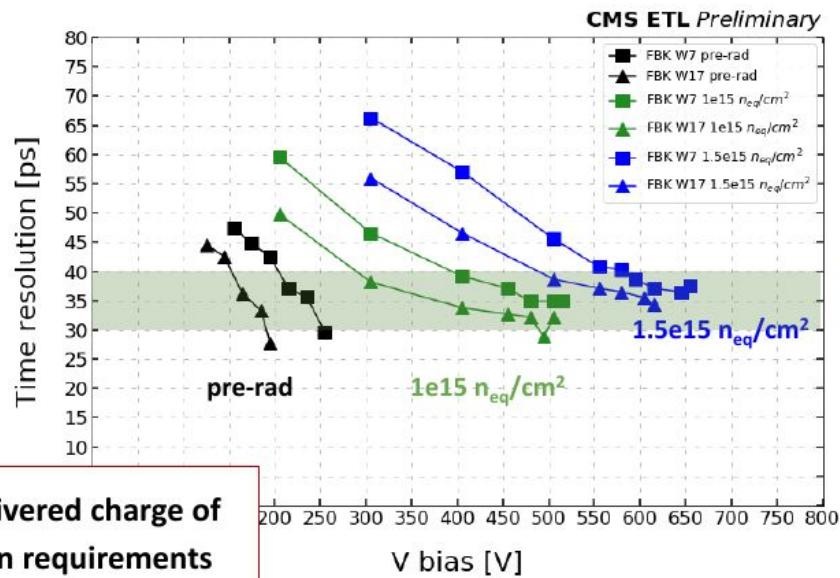
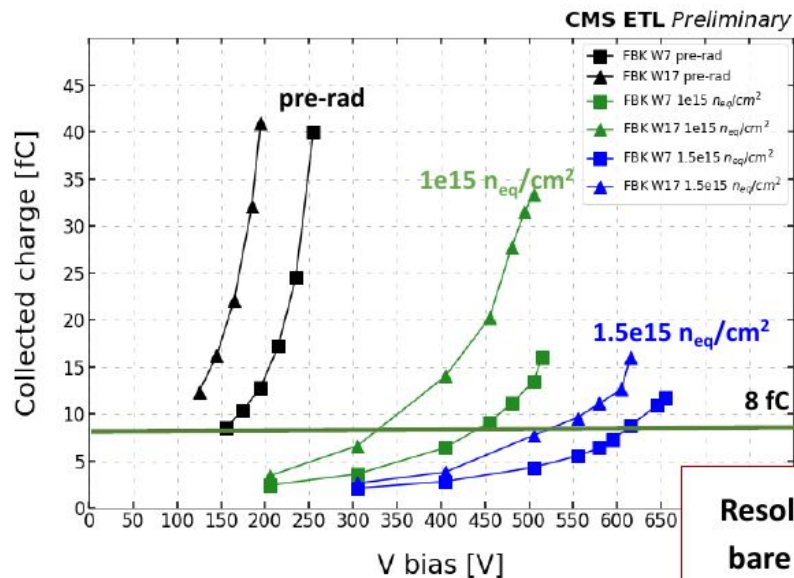
# Performance of LGADs

- Timing resolution measurements have been performed in Torino and at Fermilab
  - Using beta-source setups  $^{90}\text{Sr}$  (2 MeV)
  - Very fast low noise electronic
  - Temperature  $-25\text{ }^\circ\text{C}$
  - For different fluencies



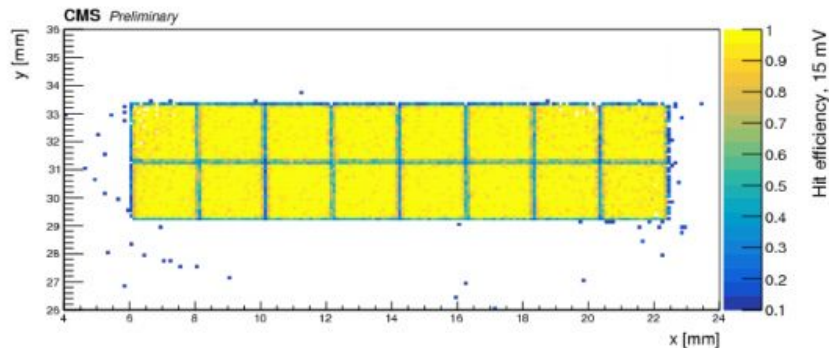
# Performance of LGADs

Example of MS sample performance: FBK (55 microns thick) measured with a beta-source setup



Resolution and delivered charge of bare sensors within requirements

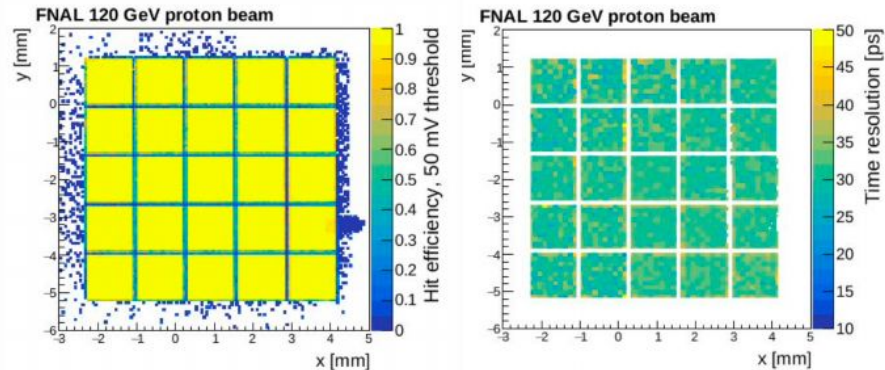
# Performance of LGADs



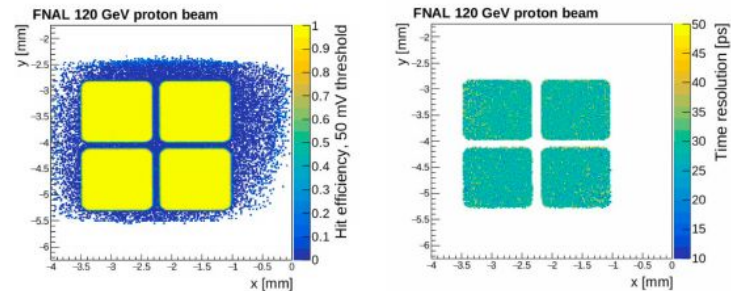
FBK 2 × 8 array (first prototype sensor production)

Irradiated  $8e14 n_{eq}/cm^2$

- ❖ Maps measured at FNAL
- ❖ Resolution for non irradiated sensors ~ 30 ps
- ❖ Hit efficiency
  - reaches ~ 100 % for non irr.
  - reaches ~ 99 % for irr.



Non-irradiated FBK 5x5 array

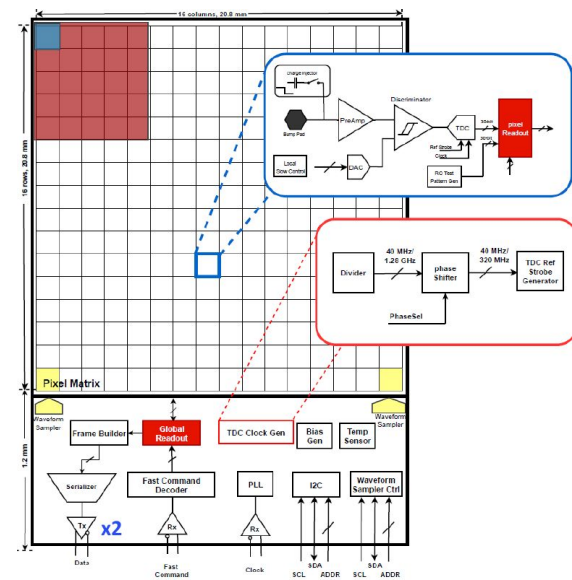


Non-irradiated IHEP IME 2x2 array



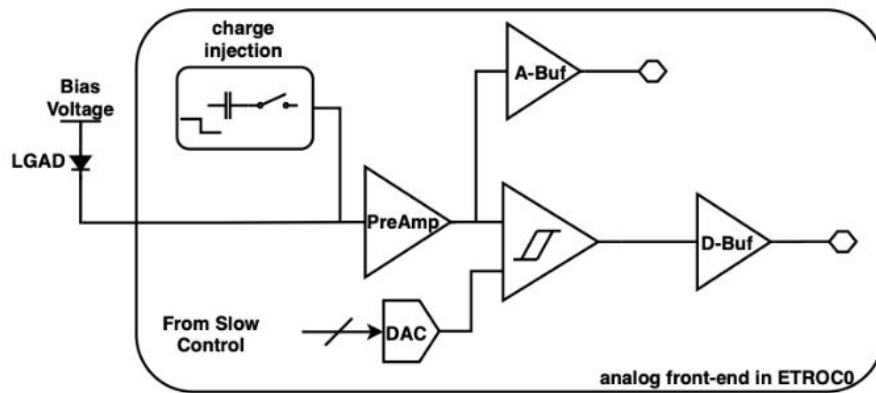
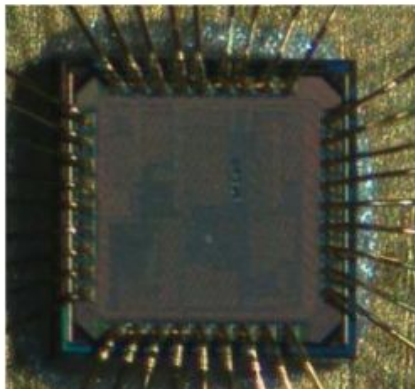
# ETL Read-Out Chip (ETROC)

- ❖ ETROC is the ETL read-out ASIC
- ❖ Electronics needs to read all the channels, it's brand new, never been done before
- ❖ **ETROC+LGAD** should achieve a time resolution  $< 50$  ps per single hit
  - 65 nm technology, 100 MRad (TID spec)
  - low noise + fast rise time
  - power budget: 1 W/chip, 3 mW/channel
  - ETROC measures arrival time of signal (6 –20 fC)
  - **ASIC** contribution to time resolution  $< 40$  ps
  - L1 buffer latency: 12.5 us
  - ENC =  $\sim 0.3$  fC
- ❖ ETROC is developed in stages (ETROC0/1/2/3)



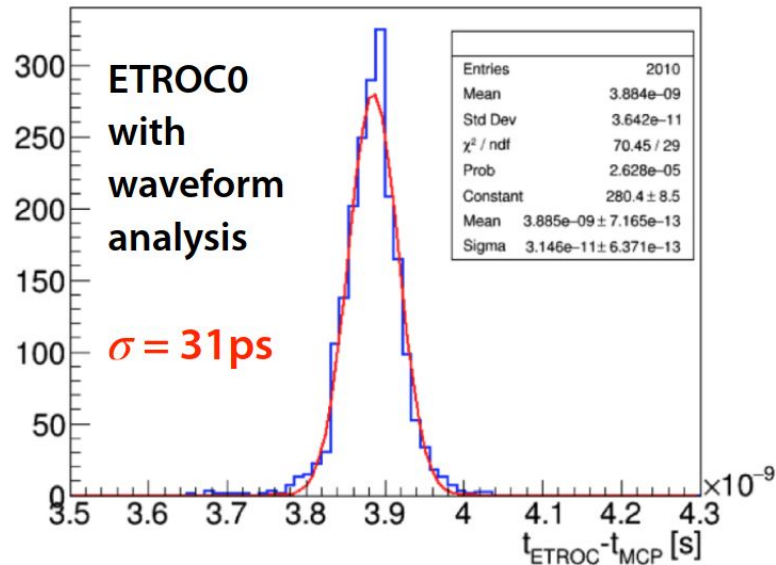
Showcase of ETROC 2 design

# ETROC0

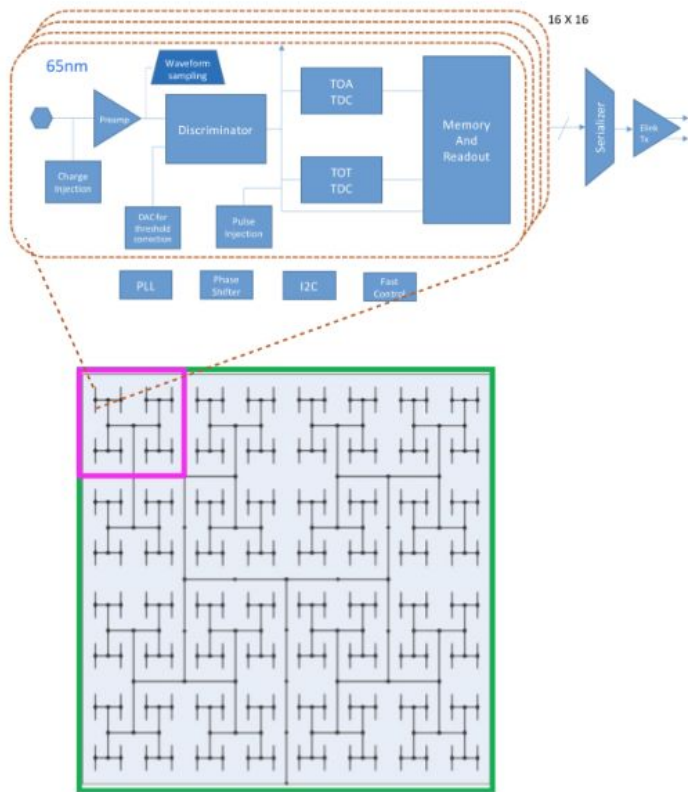


## ❖ ETROC0

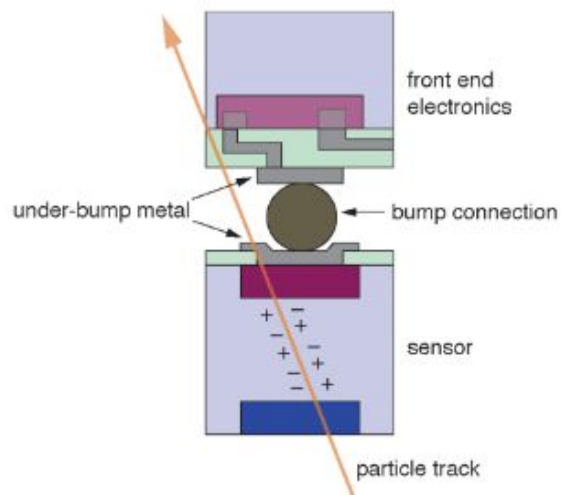
- Single analog channel
- Pre-amp + discriminator
- TID up to 100 Mrad
- 30 ~ 40 ps time resolution in test beam



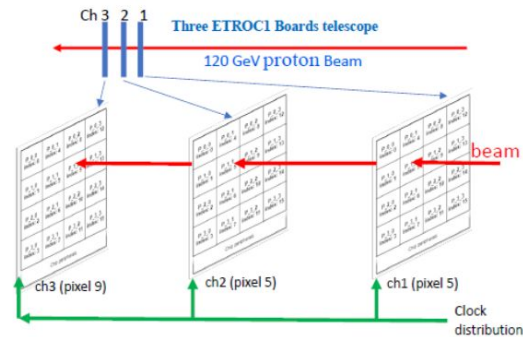
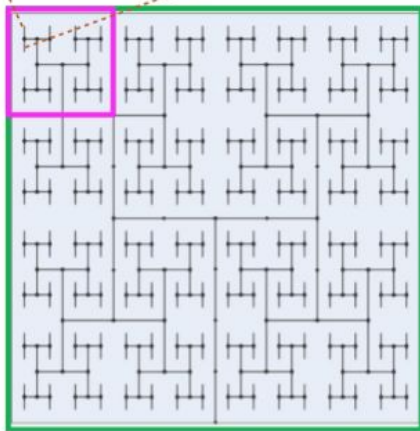
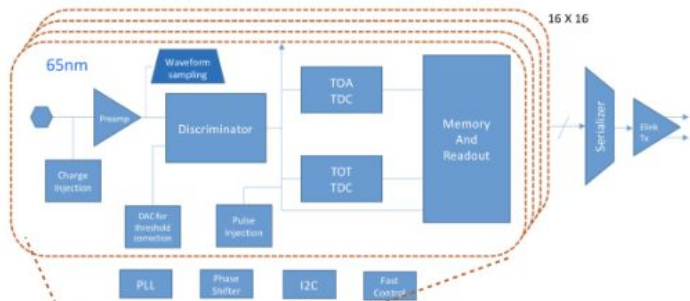
# ETROC1



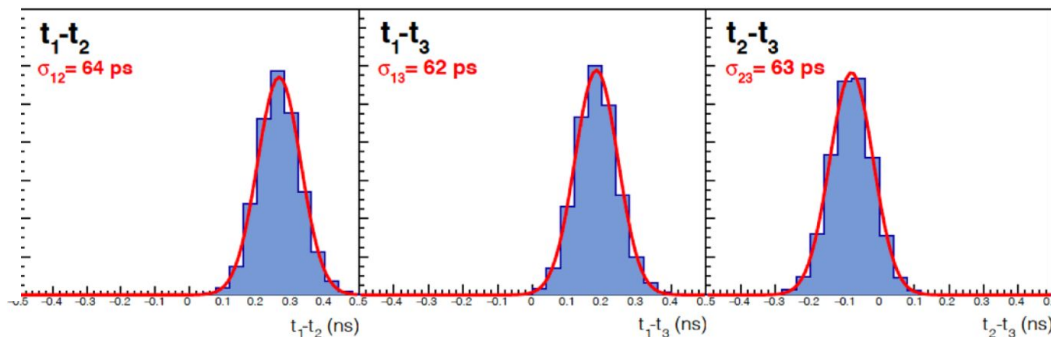
- ❖ **ETROC1**: with TDC, 4x4 channel - clock tree
- ❖ **ETROC1** proved to be able to reach **~40 ps** resolution when coupled to LGAD (measured at FNAL with 120 GeV proton beam)



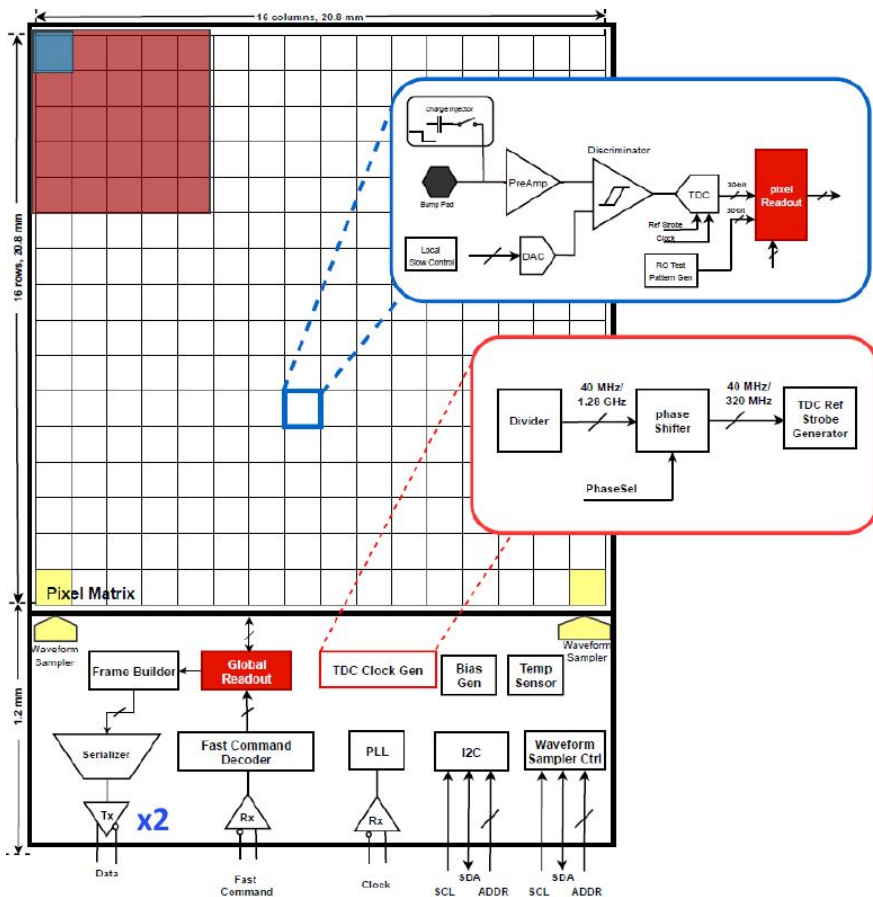
# ETROC1



$$\sigma_i = \sqrt{0.5 \cdot (\sigma_{ij}^2 + \sigma_{ik}^2 - \sigma_{jk}^2)} \sim 42 - 46 \text{ ps}$$



# ETROC2



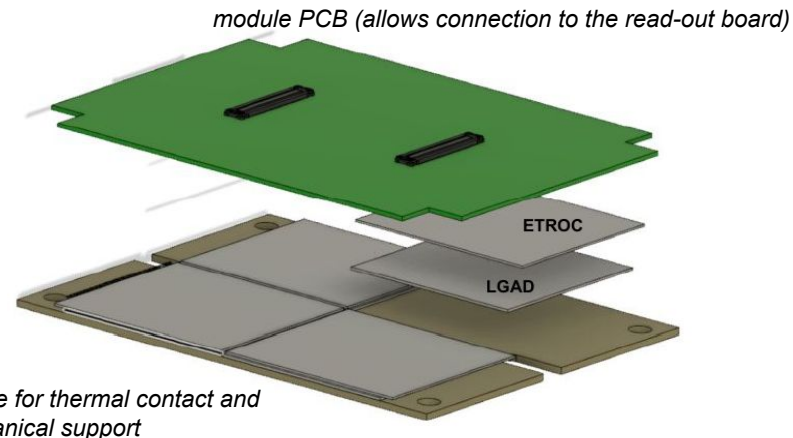
- ❖ ETROC2: full size, full functionality
- ❖ ETROC2 + LGAD testing coming soon 2023/24:
  - First, beta source and laser tests with wire-bonded LGAD
  - Build experience and debug → bump-bonded LGAD in beam

ETROC0: single analog channel  
ETROC1: with TDC, 4x4 channel - clock tree  
ETROC2: full size, full functionality  
ETROC3: final chip!

# ETROC Assembly

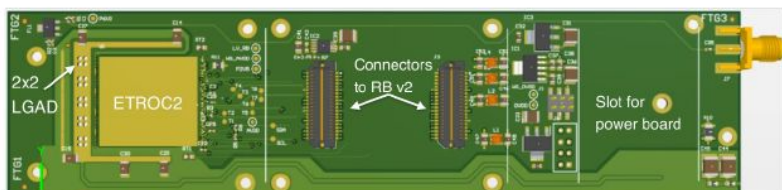
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- ❖ Modules are based on 4 16x16 pixel LGAD sensors, bump bonded to one ETROC each
- ❖ Sensors are glued on AlN baseplate and in thermal contact with the cooling
- ❖ Wire bonds to PCB Modules are directly connected to multi-module readout board that sits on top disk
- ❖ Readout board based on CERNs rad-hard Low Power Gigabit Transceiver (lpGBT) and Optical Link Module (VTRx+)

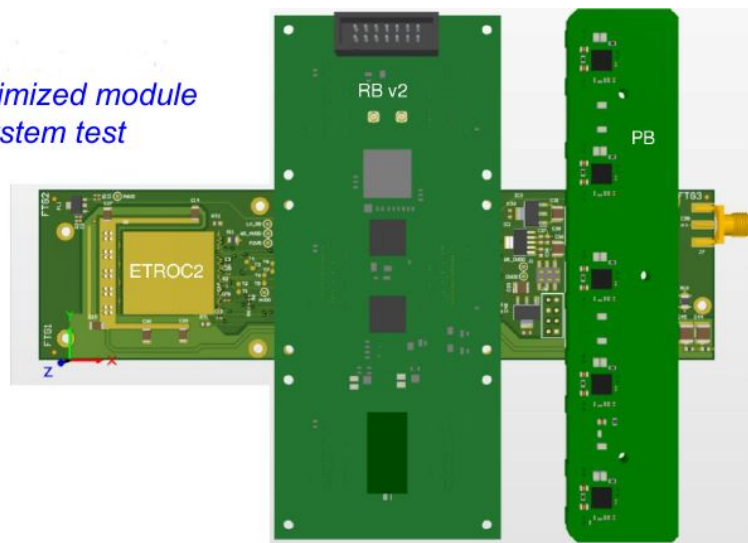


# ETROC2

- ❖ Designing a testing-optimized module compatible with ETROC2, read-out board and power board, and with a bump-bonded 16x16 → will enable a full system test!



*testing-optimized module  
for system test*



# Summary

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- ❖ The design of MTD is heavily influenced by harsh conditions of radiation
- ❖ LGAD sensors will be used, providing resolution of  $< 50$  ps, with collected  $\sim 10$  fc of charge
- ❖ MS performanse gives good results (shown for FBK)
- ❖ ETROC1 + LGAD reaches desired resolution of  $\sim 40$ -50 ps
- ❖ Full-size read-out chip ETROC2 arriving soon
- ❖ Top priority of the next months: validation of LGAD + ETROC2 based prototypes



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THANK YOU FOR YOUR  
ATTENTION

# BACKUP

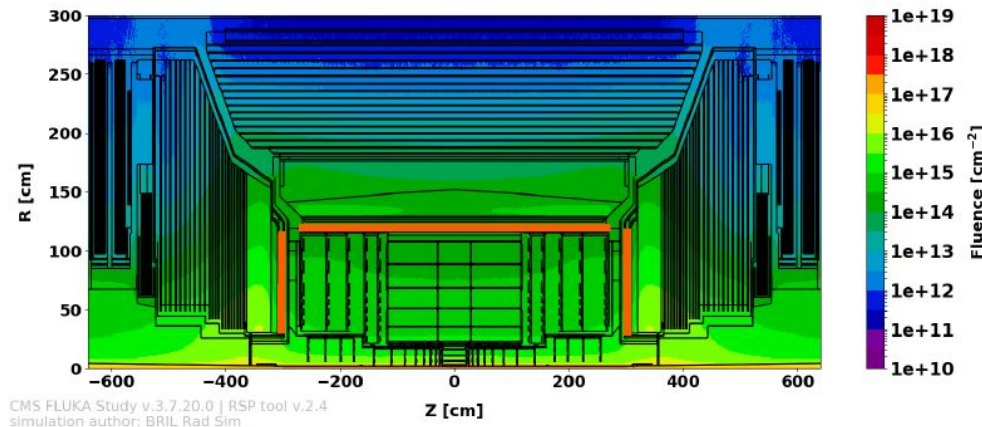
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# High Luminosity LHC (HL-LHC)

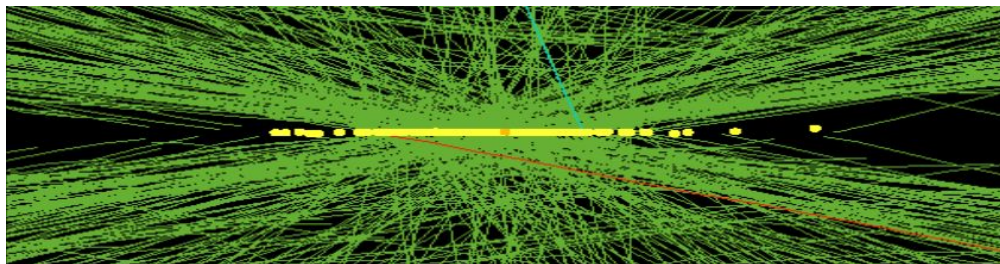
- Up to **5x** higher vertex density
- Unprecedented radiation levels
  - ~10x higher than present LHC
  - Expected fluence up to several  $10^{16}$  neq/cm<sup>2</sup>

for internal CMS use only

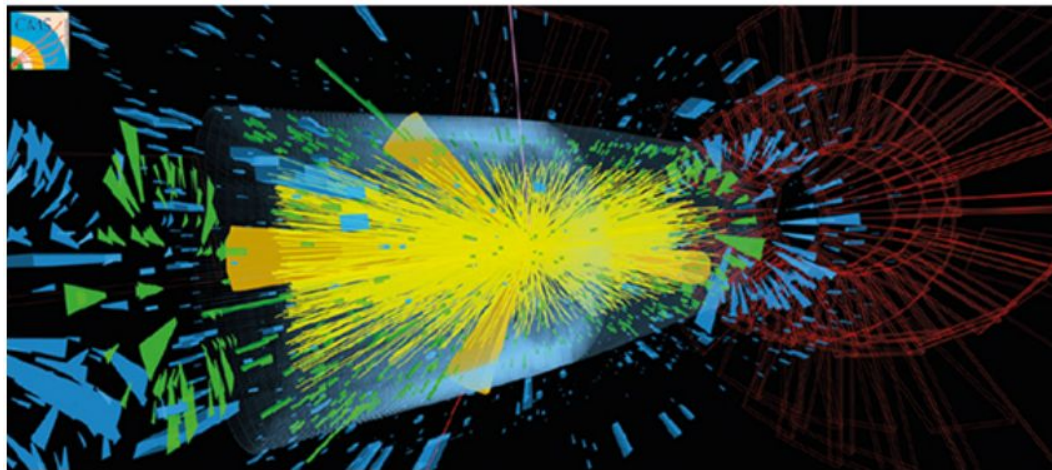
CMS Phase2 HGCalMod pp 7TeV FLUKA v3.7.20.0 :  
1 - MeV neutron equivalent Si (Central Detectors)  
4000.0 fb<sup>-1</sup> ( $\sigma_{inel} = 80.0$  mb)



- Expected fluence dictates the technology development for subdetectors



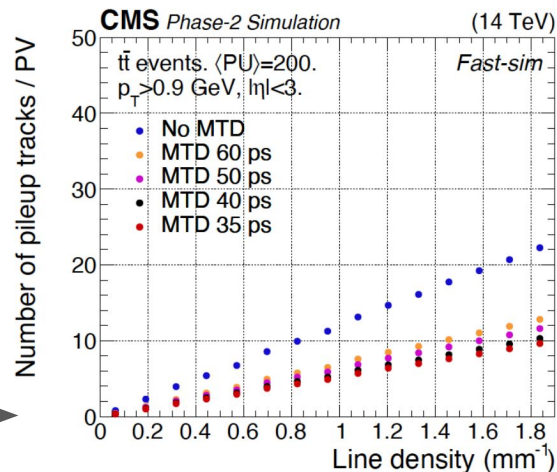
# Motivation for Tracker upgrade



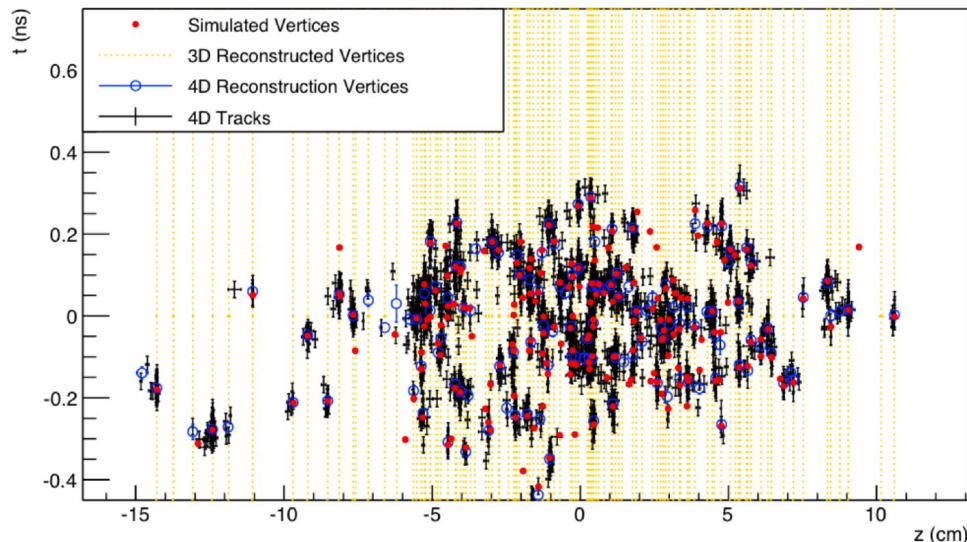
**VBF  $H \rightarrow \tau \tau$**   
**simulation 200 pp pile-up**

Interactions are distributed  
over time (and space) with an  
RMS of **180-200 ps**

Simulation: Number of pileup tracks incorrectly associated with the hard interaction vertex as a function of the collision line density for different time resolution and time reconstruction efficiency of 0.85



# Motivation for Tracker upgrade

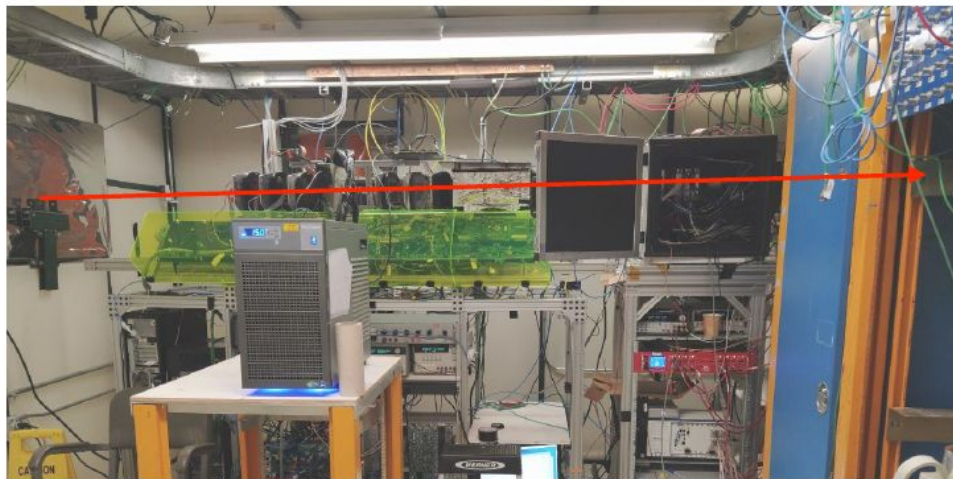


With a resolution of **35 ps**,  
vertex merging is reduced from  
**15%** in space to **1%** in  
space-time, as in the current  
operating mode of the LHC

## ❖ The MIP Timing Detector (MTD)

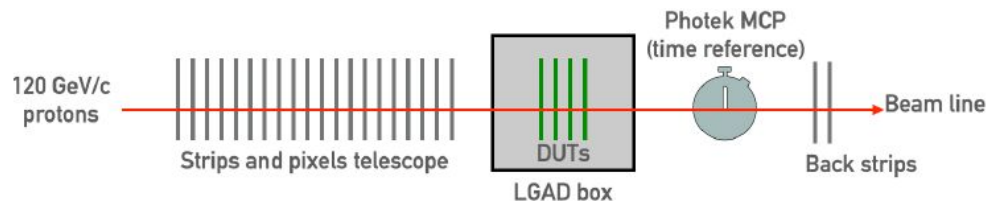
- Will measure the time of passage of charged particles with a resolution of **30-40 ps**
- This precision will decrease to **50-60 ps** towards the end of the HL-LHC operation
- In addition to being "fast", it must be able to withstand harsh conditions/radiation
- Charged tracks/vertices association with photons and hadronic showers

# LGAD sensors - FermiLab test



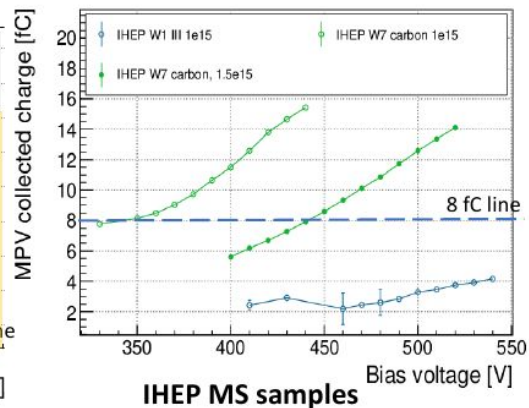
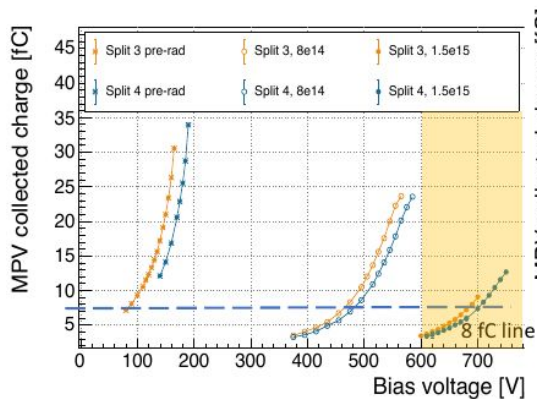
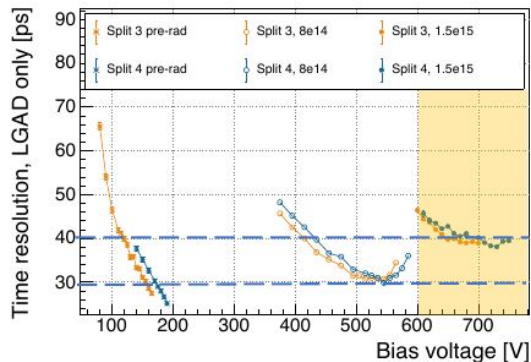
- ❖ Proton beam 120 GeV/c
- ❖ Scintillator used as a trigger
- ❖ Telescope monitors the position
- ❖ MCP (resolution 10ps) for time reference
- ❖ Cooling chamber

2021

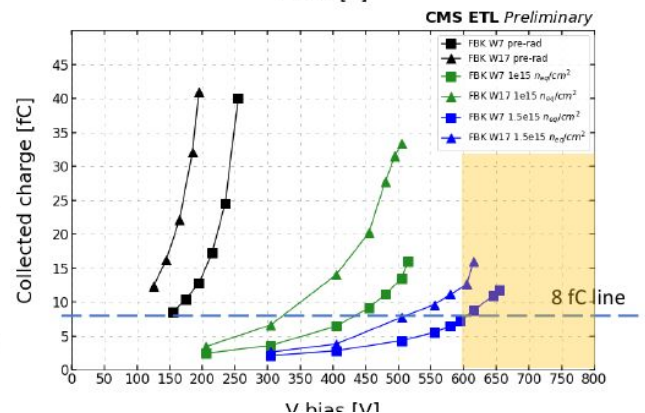
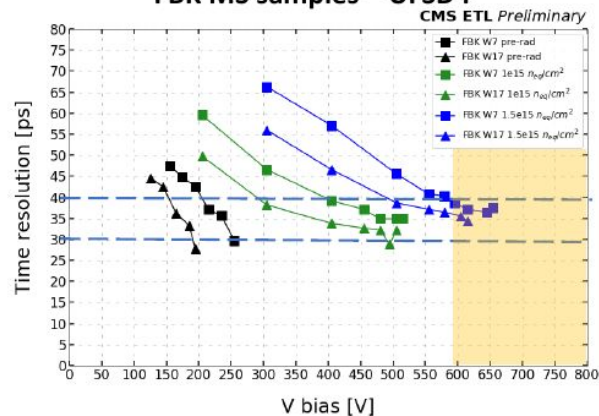


# LGADs: Time resolution - charge collected

HPK MS samples – HPK2



FBK MS samples – UFSD4



# Desy TeastBeam, November 2022

Siviero F. , MTD ETL sensors qualification and test plans, CMS upgrade Days 2023

- **First test beam ever with 16x16 LGADs**
  - Previous ones only with small prototypes
- Three vendors tested: HPK, FBK, IHEP-IME
- **Very nice agreement with previous results from small prototypes**
- **All sensors achieved the target performance both in terms of time resolution and delivered charge**

